www.koolance.com

Specifications Sheet

Generated: 2026-11-18

P/N: CPU-370

CPU-370 Water Block, Rev1.1 (AMD/Intel Processor)



The CPU-370 contains an advanced microfin cold plate (0.25mm fins, 0.30mm channels), o-ring sealed impingement plate, and an optimized flow path minimize coolant restriction.

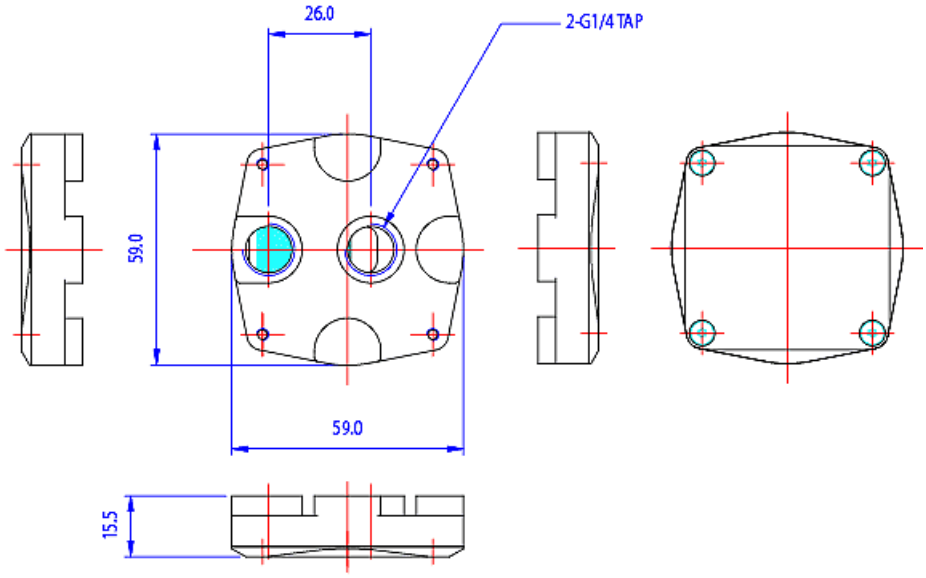
The CPU-370 contains a copper cold plate with brass top. As with all Koolance products, nickel plating is added to improve corrosion resistance. Two universal steel mounting brackets are included for mainstream Intel and AMD processors. The CPU-370 has standard G 1/4 BSPP threading for any Koolance fitting diameter. Fitting sockets are placed far apart to allow for extra wide compression fittings. Please select the desired fitting type for this base model (it does not include fittings).

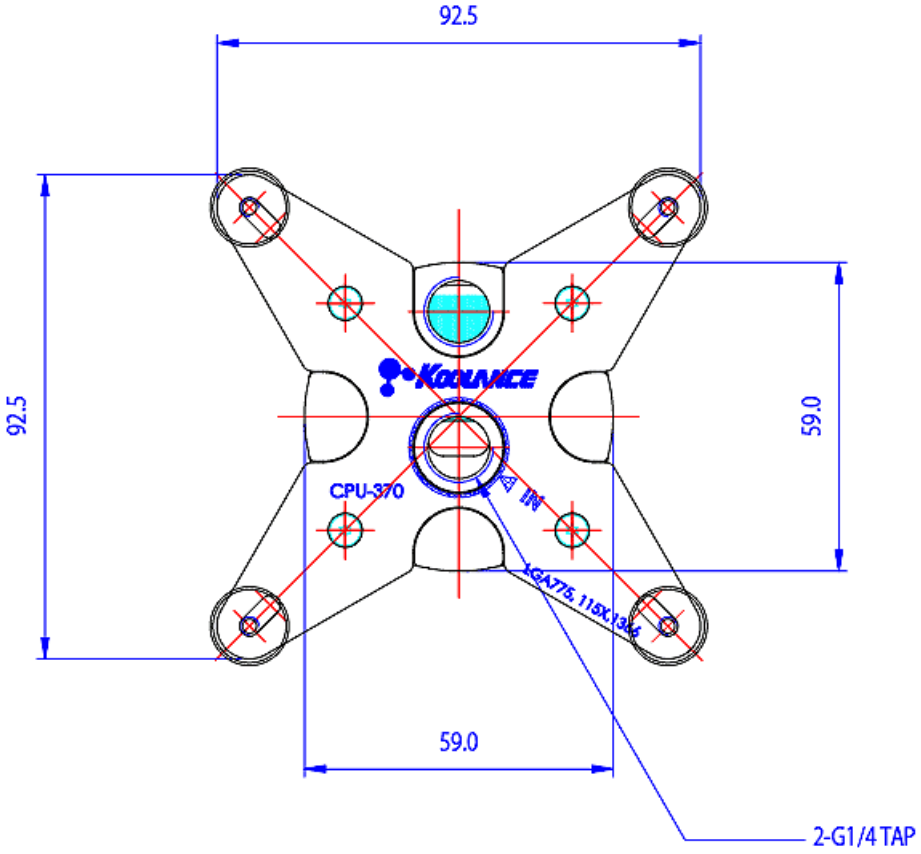
The CPU-370 supports most boards using the following processors:

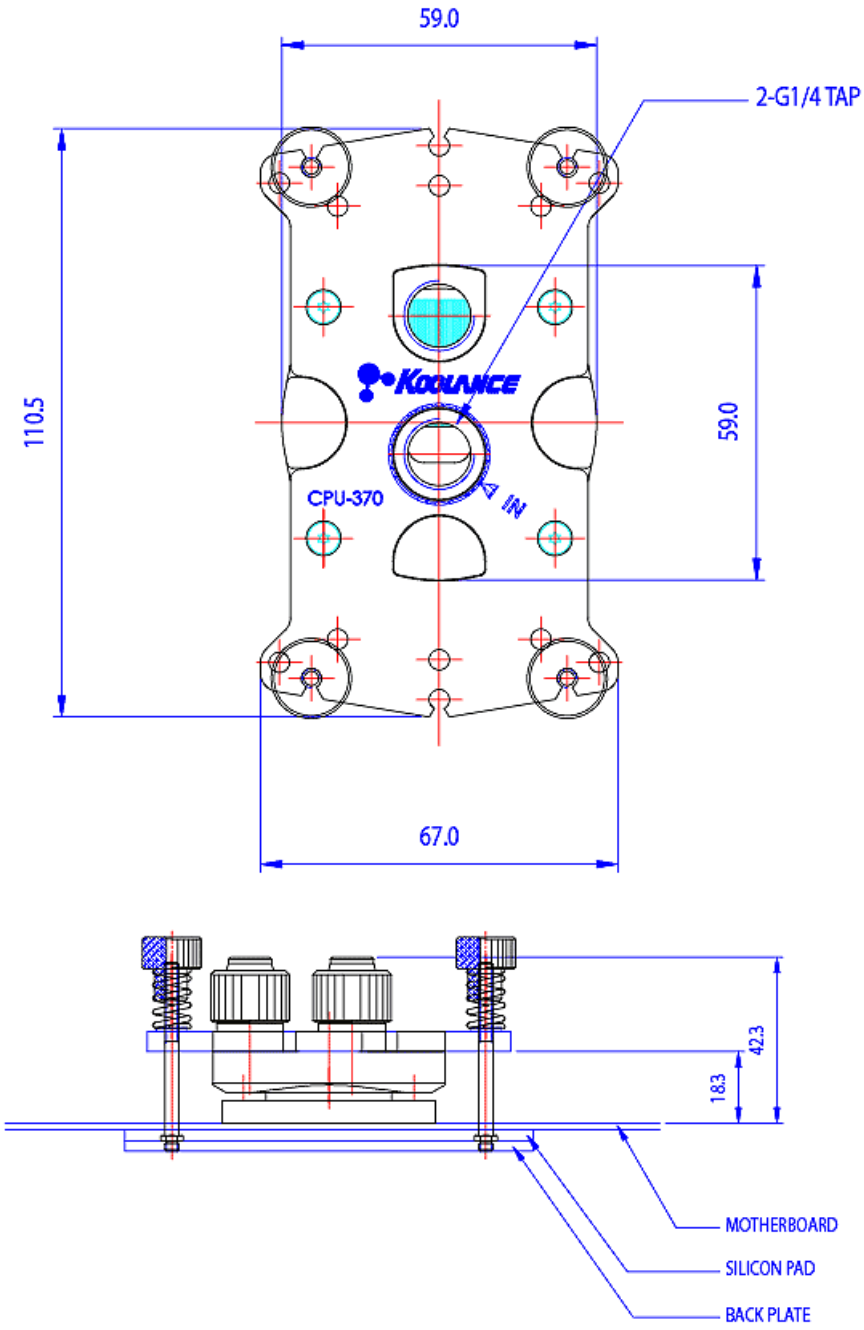
- AMD socket AM2, AM2+, AM3, AM3+, FM1, FM2
- AMD socket 1207(F)/C32, 939, 940 (with separate BKT-CP021K)
- AMD socket G34 (with separate BLT-CPAMDG34)
- Intel socket LGA 2011
- Intel socket LGA 1155/1156
- Intel socket LGA 1366 (may require BLT-CPASZD12 if motherboard back plate is fixed)
- Intel socket LGA 775

Hybrid Thermal Solution: ready for air and water cooling
With its sharp ROG style, the ROG Hybrid Thermal Solution is more than just a VRM cooler: it combines a 100% copper watercooling channel with electroplated nickel barbs and an integrated heatpipe, all wrapped in air-cooling fins. With the choice of both water-cooling or air-cooling, Hybrid Thermal Solution delivers the ultimate add-on to achieve that OC advantage.

General	
Weight	0.80 lb (0.36 kg)
Wetted Materials	Nickel-Plated Copper, Nickel-Plated Brass, Stainless Steel, EPDM


26.0
2-G1/4 TAP
59.0
59.0
15.5


92.5
92.5
59.0
CPU-370
IN
LGA775, 115X/1366
59.0
2-G1/4 TAP


59.0
2-G1/4 TAP
110.5
59.0
KOOLANCE
CPU-370
IN
67.0
42.3
18.3
MOTHERBOARD
SILICON PAD
BACK PLATE